



Click [here](#) for the 3D model.

### Dimensions

|           |                  |
|-----------|------------------|
| Chip Size | 0603             |
| L         | 1.6mm +/-0.15mm  |
| W         | 0.8mm +/-0.15mm  |
| T         | 0.8mm +/-0.07mm  |
| S         | 0.7mm MIN        |
| B         | 0.35mm +/-0.15mm |

### Packaging Specifications

|                    |                        |
|--------------------|------------------------|
| Packaging          | T&R, 330mm, Paper Tape |
| Packaging Quantity | 15000                  |

### General Information

|                  |   |
|------------------|---|
| Series           | ESD SMD Comm X7R  |
| Style            | SMD Chip  |
| Description      | SMD, MLCC, Temperature Stable, Electro Static Discharge, Class II |
| Features         | Temperature Stable, Class II                                      |
| RoHS             | Yes   |
| Termination      | Tin   |
| Marking          | No  |
| AEC-Q200         | No  |
| Component Weight | 4.8 mg  |
| Shelf Life       | 78 Weeks  |
| MSL              | 1   |

### Specifications

|  |  |
|--|--|
| Capacitance  | 0.033 uF   |
| Measurement Condition  | 1 kHz 1.0Vrms                                      |
| Capacitance Tolerance  | 5%   |
| Voltage DC   | 16 VDC   |
| ESD Level per AEC-Q200   | 25,000 V ESD Level                                 |
| Dielectric Withstanding Voltage                                    | 40 VDC   |
| Temperature Range  | -55/+125°C   |
| Temperature Coefficient  | X7R  |
| Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC) | 15%, 1kHz 1.0Vrms                                  |
| Dissipation Factor   | 3.5% 1 kHz 1.0Vrms                                 |
| Aging Rate   | 3% Loss/Decade Hour:<br>Referee Time is 1000 Hours |
| Insulation Resistance  | 30.303 GOhms                                       |